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Electronic Version v1.1

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Title of Invention	Elimination of RDk Using Tape Base Flip Chip on Flex for Die Stacking	
Application Number :	10/050507	
Date :	2002-01-16	
First Named Applicant:	Lee Teck	
Confirmation Number:	7687	
Attorney Docket Number:	MTI-31607	
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Submitted By: Kristine M. Strodthoff Registered Number: 34259		Elec. Sign. /kxs/ Sign. Capacity Attorney

Documents being submitted:	Files
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